Compositions for diffusion patterning

Description of Technology: The invention is directed to non-photoformable polymeric compositions which are especially suitable for use in diffusion patterning.

Patent Listing:
1. **US Patent No. 5,654,354**, Issued August 5, 1997, "Compositions for diffusion patterning"
   http://patft.uspto.gov/netacgi/nph-Parser?Sect2=PTO1&Sect2=HITOFF&p=1&u=%2Fnetahtml%2FPTO%2Fsearch-bool.html&r=1&f=G&l=50&d=PALL&RefSrch=yes&Query=PN%2F5654354

Market Potential: Thick film technology has historically been an attractive method of producing conductors, dielectrics and resistors that are rugged and reliable. The technology is well suited for economical production of short production runs. Its ability to be patterned in multilayer configurations has allowed fabrication of devices with namely high circuit density. The successive levels of conductors in the multilayer structure are separated by insulating dielectric layers and are interconnected by vias through the dielectric layers.

Benefits:
- Patterned in multilayer configurations allows fabrication of devices with high circuit density

Applications:
- Polymer films and polymeric compositions